

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0	1.58	0.06
	Doped silicon	Silicon (Si)	7440-21-3	0.19	98.42	3.74
Subtotal				0.19	100	3.8
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01	10.0	0.25
	Silver alloy	Silver (Ag)	7440-22-4	0	2.0	0.05
	Lead alloy	Lead (Pb)	7439-92-1	0.11	88.0	2.23
Subtotal				0.12	100	2.53
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.07	100.0	1.31
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.4
	Copper alloy	Iron (Fe)	7439-89-6	0.04	0.06	0.8
	Copper alloy	Copper (Cu)	7440-50-8	67.3	99.91	1338.79
Subtotal				67.36	100	1339.99
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.04	100.0	20.68
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.4	4.5	27.95
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.12	10.0	62.1
	Filler	Silica fused	60676-86-0	23.41	75.0	465.75
	Metal hydroxide	Metal hydroxide		3.12	10.0	62.1
	Carbon Black	Carbon black	1333-86-4	0.16	0.5	3.1
Subtotal				31.21	100	621
Total				99.99	100	1989.31

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.